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Design of Origami Fin for Heat Dissipation Enhancement

Xu Wang, Hanqing Jiang

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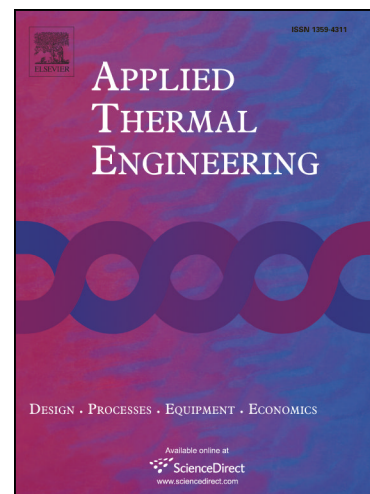
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Xu Wang^{1,*}, Hanqing Jiang¹

¹School for Engineering of Matter, Transport and Energy, Arizona State University, Tempe, AZ
85287, USA

*Email: xwang287@asu.edu

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